

ABSTRACT

An elongated bonding pad comprises two areas, a bonding area and an elongated probing area. The bonding area is located on the edge of an integrated circuit device for wire bonding. The elongated probing area is located on the inner area of the device. The long dimension of the elongated probing area is large enough for carrying a probing mark and the short dimension of the probing area is electrically and mechanically connected to the bonding area. Such elongated bonding pad can reduce the possibility of bonding wire open failures caused by wafer sort probing and increase the device's capacity of hosting more electrical components.